DRC5144G

Silicon NPN epitaxial planar type

For digital circuits Complementary to DRA5144G DRC2144G in SMini3 type package

■ Features

- ullet Low collector-emitter saturation voltage $V_{\text{CE(sat)}}$
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	50	V	
Collector-emitter voltage (Base open)	V _{CEO}	50	V	
Collector current	I_{C}	100	mA	
Total power dissipation	P_{T}	150	mW	
Junction temperature	T_j	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

■ Package

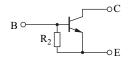
• Code

SMini3-F2-B

- Pin Name
 - 1: Base
 - 2: Emitter
 - 3: Collector

■ Marking Symbol: NU

■ Internal Connection



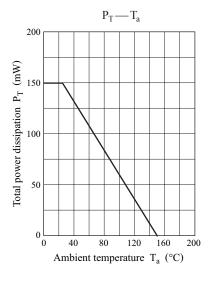
Resistance value	R ₂	47	kΩ

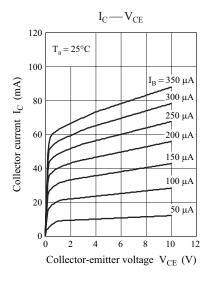
■ Electrical Characteristics $T_a = 25$ °C±3°C

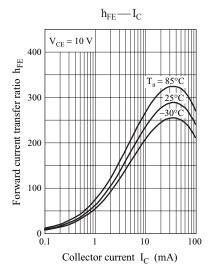
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = 10 \mu A, I_{\rm E} = 0$	50			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = 2 \text{ mA}, I_B = 0$	50			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{\rm CB} = 50 \text{ V}, I_{\rm E} = 0$			0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = 50 \text{ V}, I_{B} = 0$			0.5	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 6 \text{ V}, I_C = 0$			2.0	mA
Forward current transfer ratio	h_{FE}	$V_{CE} = 10 \text{ V}, I_{C} = 5 \text{ mA}$	80			_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 10 \text{ mA}, I_B = 0.5 \text{ mA}$			0.25	V
Input voltage (ON)	V _{I(on)}	$V_{CE} = 0.2 \text{ V}, I_{C} = 5 \text{ mA}$	0.9			V
Input voltage (OFF)	V _{I(off)}	$V_{CE} = 5 \text{ V}, I_{C} = 100 \mu\text{A}$			0.4	V
Input resistance	R ₂		-30%	47	+30%	kΩ

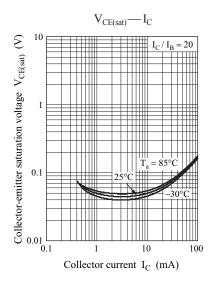
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

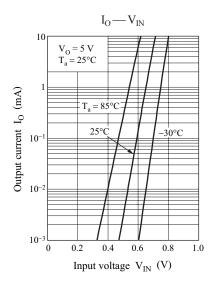
DRC5144G Panasonic

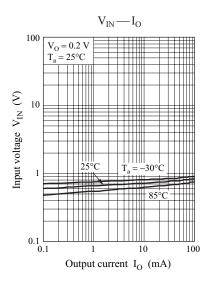










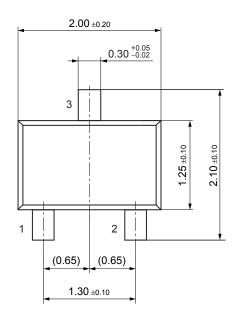


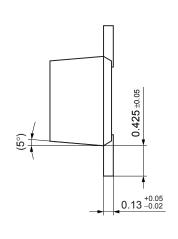
2 Ver. BED

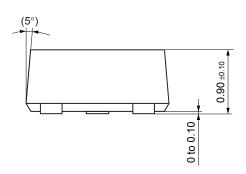
Panasonic DRC5144G

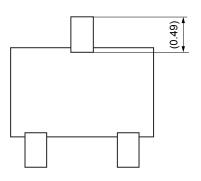
SMini3-F2-B

Unit: mm









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